L Number	Hits	Search Text	DB	Time stamp
1	30274	(planariz\$5 or polish\$3) with (metal or copper)	USPAT;	2003/06/18 08:23
			US-PGPUB;	
			EPO; JPO;	
	,		DERWENT;	
			IBM_TDB	
8	25573	(planariz\$5 or polish\$3) with etch\$4	USPAT;	2003/06/18 08:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	6082	((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 08:24
}		etch\$4)	US-PGPUB;	
			EPO; JPO;	
ĺ I			DERWENT;	
			IBM TDB	
22	1515	(((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)	USPAT;	2003/06/18 09:40
}			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
29	54	((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 09:40
		etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (etch\$4 with (nitric or	US-PGPUB;	
}		("HNO.sub.3")))	EPO; JPO;	
]		(DERWENT;	
}			IBM_TDB	·
36	57	((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 08:29
	0.	etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (etch\$4 with	US-PGPUB;	
}		(hydrochloric or "HCI"))	EPO; JPO;	
	•		DERWENT;	
			IBM_TDB	
43	105	(((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 08:29
"	,	etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (etch\$4 with (nitric or	US-PGPUB;	
		("HNO.sub.3")))) or (((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5	EPO; JPO;	
	(or polish\$3) with etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and	DERWENT;	
		(etch\$4 with (hydrochloric or "HCl")))	IBM_TDB	
50	181	((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT:	2003/06/18 09:50
		etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (planariz\$5 same	US-PGPUB;	
1		(etchant\$1 or gas)) and plasma	EPO; JPO;	
		(and passes gas, and passes	DERWENT:]
			IBM_TDB	
57	172	(((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 10:28
]		etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (planariz\$5 same	US-PGPUB;	
		(etchant\$1 or gas)) and plasma) and ((dry adj etch\$3) or (plasma with etch\$3) or (ion	EPO; JPO;	
1		adj etch\$3) or RIE)	DERWENT;	}
[IBM_TDB	
64	67	((((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (planariz\$5 same (etchant\$1 or gas)) and plasma) and ((dry adj etch\$3) or (plasma with etch\$3) or (ion adj etch\$3) or RIE)) and (planariz\$5 with (etchant\$1 or gas))	USPAT:	2003/06/18 09:52
}			US-PGPUB:	
			EPO; JPO;	ļ Ī
			DERWENT;	
		,	IBM_TDB]
78	97	(((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (planariz\$5 same	USPAT;	2003/06/18 10:29
			US-PGPUB;	
		(etchant\$1 or gas)) and plasma) and (planariz\$5 with((dry adj etch\$3) or (plasma with	EPO; JPO;	1
		etch\$3) or (ion adj etch\$3) or RIE))	DERWENT;	
			IBM_TDB	J

85	40	((((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with	USPAT;	2003/06/18 10:30
	}	etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and (planariz\$5 same	US-PGPUB;	
		(etchant\$1 or gas)) and plasma) and (planariz\$5 with((dry adj etch\$3) or (plasma with	EPO; JPO;	
]		etch\$3) or (ion adj etch\$3) or RIE))) not (((((planariz\$5 or polish\$3) with (metal or	DERWENT;	
		copper)) and ((planariz\$5 or polish\$3) with etch\$4)) and (planariz\$5 with (metal or	IBM_TDB	
	ļ	copper) with etch\$4)) and (etch\$4 with (nitric or ("HNO.sub.3")))) or (((((planariz\$5 or		ļ
	1	polish\$3) with (metal or copper)) and ((planariz\$5 or polish\$3) with etch\$4)) and		
]	(planariz\$5 with (metal or copper) with etch\$4)) and (etch\$4 with (hydrochloric or		ļ
		"HCl")))) not ((((((planariz\$5 or polish\$3) with (metal or copper)) and ((planariz\$5 or		
		polish\$3) with etch\$4)) and (planariz\$5 with (metal or copper) with etch\$4)) and		
	•	(planariz\$5 same (etchant\$1 or gas)) and plasma) and ((dry adj etch\$3) or (plasma		
		with etch\$3) or (ion adj etch\$3) or RIE)) and (planariz\$5 with (etchant\$1 or gas)))		

L Number	Hits	Search Text	DB	Time stamp
1	439	stray\$2 near4 metal	USPAT;	2003/06/18 15:44
			US-PGPUB;	
	:		EPO; JPO;	,
	•		DERWENT;	
			IBM_TDB	
8	20	(stray\$2 near4 metal) and 438/\$7	USPAT;	2003/06/18 15:47
	_,		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	12	(stray\$2 near4 metal) and 438/\$7.FS.	USPAT;	2003/06/18 15:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	14	((stray\$2 near4 metal) and 438/\$7) not ((stray\$2 near4 metal) and 438/\$7.FS.)	USPAT;	2003/06/18 15:55
'	•	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
23	83	(stray\$2 near4 metal) and (deposit\$3 with metal)	USPAT;	2003/06/18 15:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
30	20	((stray\$2 near4 metal) and (deposit\$3 with metal)) and 438/\$7.ccls.	USPAT;	2003/06/18 15:58
		((000) +2 110011 + 11100111 (1110) +11100111 (1110)	US-PGPUB;	
			EPO; JPO;	
ļ			DERWENT;	
			IBM_TDB	
37	9	(((stray\$2 near4 metal) and (deposit\$3 with metal)) and 438/\$7.ccls.) not ((stray\$2	USPAT;	2003/06/18 15:58
		near4 metal) and 438/\$7)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	